MA2Z372 (MA372)

Silicon epitaxial planar type

For UHF and VHF electronic tuners

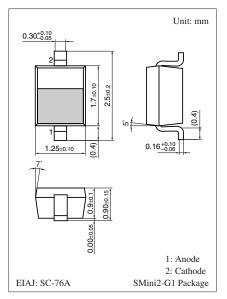
■ Features

- Large capacitance ratio
- Small series resistance r_D
- S-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	32	V
Maximum peak reverse voltage *	V _{RM}	34	V
Forward current	I_F	20	mA
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Note) *: $R_L = 2.2 \text{ k}\Omega$



Marking Symbol: 6N

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I_R	$V_R = 30 \text{ V}$			10	nA
Diode capacitance	C _{D(2V)}	$V_R = 2 \text{ V}, \text{ f} = 1 \text{ MHz}$	14.220		15.473	pF
	C _{D(25V)}	$V_R = 25 \text{ V}, f = 1 \text{ MHz}$	2.132		2.321	
	C _{D(10V)}	$V_R = 10 \text{ V, f} = 1 \text{ MHz}$	5.307		6.128	
	C _{D(17V)}	$V_R = 17 \text{ V, f} = 1 \text{ MHz}$	2.909		3.411	
Capacitance ratio	C _{D(2V)} /C _{D(25V)}		6.22			_
	C _{D(10V)} /C _{D(17V)}		1.70		1.96	
Diode capacitance deviation *1	ΔC	C _{D(2V)(10V)(17V)(25V)}			2.0	%
Series resistance *2	r_{D}	$C_D = 9 \text{ pF, } f = 470 \text{ MHz}$			0.45	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

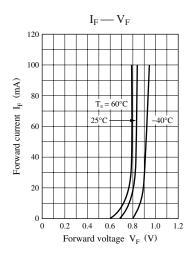
Matching is done at V_R = 2 V, 10 V, 17 V, 25 V and capacitance difference of one group diode is limited within 2.0%.

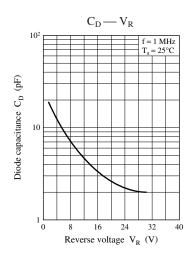
Note) The part number in the parenthesis shows conventional part number.

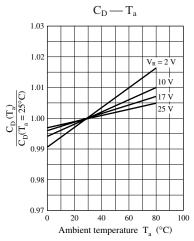
^{2.} Absolute frequency of input and output is 470 MHz.

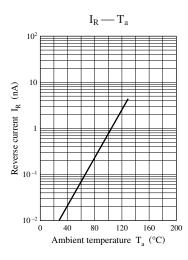
^{3. *1:} Being matching by selection:

^{*2:} Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER



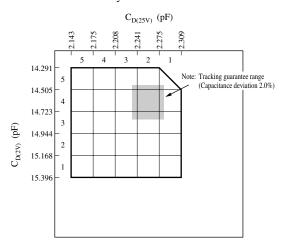




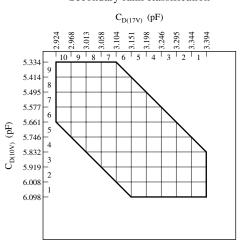


C_D rank classification

Primary rank classification



Secondary rank classification



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